ON TAT INDUSTRIAL COMPANY

SPECIFICATION

Product Model: DT280QV10-CT (Rev.B)

Designed by	R&D Checked by	Quality Department by	Approved by

Approval by Customer

OK	
NG,Problem survey:	
	Annual Dis
	Approved By

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Revision Record

REV NO.	REV DATE	CONTENTS	Note
Α	2014-04-23	NEW ISSUE	
В	2014-10-18	Modify LED Circuit	

Table Of Contents

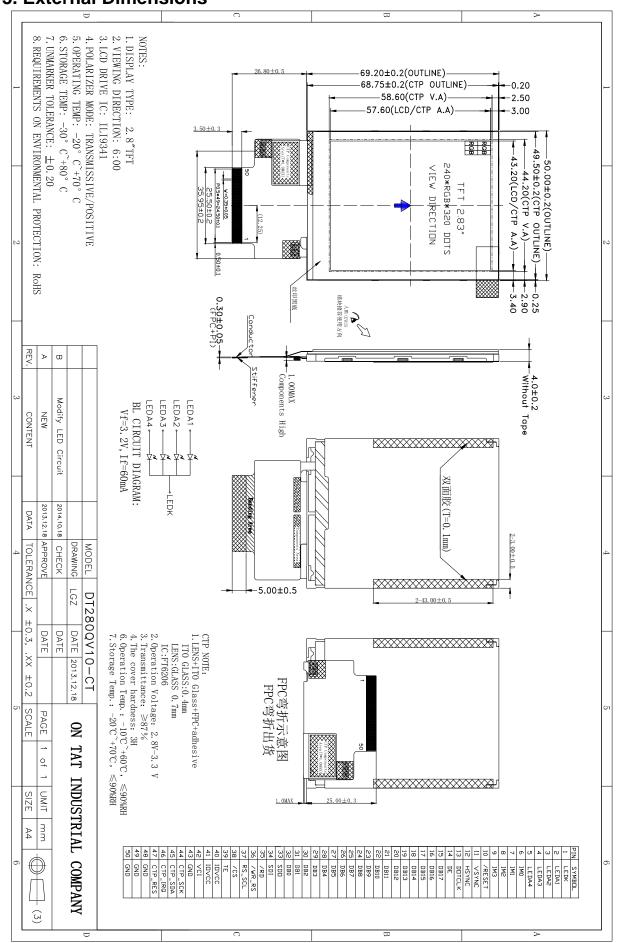
List	Description	Page No.
	Cover	1
	Revision Record	2
	Table Of Contents	3
1	Numbering System	4
2	General Information	4
3	External Dimensions	5
4	Interface Description	6
5	Absolute Maximum Ratings	7
6	Electrical Characteristics	7
7	Timing Characteristics	8
8	Backlight Characteristics	11
9	Optical Characteristics	11
10	Reliability Test Conditions And Methods	13
11	Inspection Standard	14
12	Handling Precautions	17
13	Precaution For Use	18
14	Packing Method	18

1. Numbering System

2. General Information

ITEM	STANDARD VALUES	UNITS
LCD type	2.8"TFT With CTP	
CTP type	G+G , Single point and gestures	
Dot arrangement	240(RGB)×320	dots
Color filter array	RGB vertical stripe	
Display mode	TN / Transmission / Normally White	
Viewing Direction	6 o'clock	
TFT Driver IC	ILI9341	
CTP Driver IC	FT6206	
Module size	50.0(W)×69.2(H)×4.0(T)	mm
Active area	43.2(W)×57.6(H)	mm
Dot pitch	0.18(W)×0.18(H)	mm
Interface	4-lines_8bit / 3-lines_9bit SPI 8-/ 9-/16-/18-bit 8080-series system interface 6-/16-/18-bit RGB interface	1
Operating temperature	-20 ~ +70	್ರೆ
Storage temperature	-30 ~ +80	${\mathbb C}$
Back Light	4 White LED In Parallel	
Weight	TBD	g

3. External Dimensions



4. Interface Description

<u>4. I</u>	nterrace	Description				
Pin	Symbol	Description.				
1	LEDK	LED backlight (Cathode).				
2	LED-A1	LED backlight (Anode).				
3	LED-A2	LED backlight (Anode).				
4	LED-A3	LED backlight (Anode).				
5	LED-A4	LED backlight (Anode).				
		System interface Mode				
6	IMO	IM3 IM2 IM1 IM0 Interface mode DB Pin				
		0 0 0 i80-system 8-bit interface I DB[7:0] 0 0 1 i80-system 16-bit interface I DB[15:0]				
		0 0 1 0 i80-system 9-bit interface I DB[8:0]				
7	IM1	0 0 1 1 i80-system 18-bit interface I DB[17:0]				
		0 1 0 1 3-wires_9-bit SPI I /CS,SDI,SCL				
		0 1 1 0 4-wires_8-bit SPI I /CS,RS,SDI,SCL				
8	IM2	1 0 0 i80-system 16-bit interface II DB[17:10],DB[8:1] 1 0 0 1 i80-system 8-bit interface II DB[17:10]				
		1 0 0 1 i80-system 8-bit interface				
		1 0 1 1 i80-system 9-bit interface II DB[17:9]				
9	IM3	1 1 0 1 3-wires_9-bit SPI II /CS,SDI,SDO,SCL				
		1				
10	/RESET	Reset input pin, Active "L".				
11	VSYNC	Vertical sync signal in RGB I/F.				
12	HSYNC	Horizontal sync signal in RGB I/F.				
13	DOTCLK	Pixel clock signal in RGB I/F.				
14	DE	Data enable signal in RGB I/F mode				
15	DB17					
16	DB16					
17	DB15	18-bit parallel bi-directional data bus for MPU- I system:				
18	DB14	8-bit I/F: DB[7:0] is used.				
19	DB13	9-bit I/F: DB[8:0] is used.				
20	DB12	16-bit I/F: DB[15:10] is used. 18-bit I/F: DB[17:0] is used.				
21	DB11					
22	DB10	18-bit parallel bi-directional data bus for MPU- II system:				
23	DB9	8-bit I/F: DB[17:10] is used.				
24	DB8	9-bit I/F: DB[17:9] is used.				
25	DB7	16-bit I/F: DB[17:10] and DB[8:1] is used. 18-bit I/F: DB[17:0] is used.				
26	DB6	าง-มน ทัศ. บิดี[ที .บ] is usea.				
27	DB5	18-bit input data bus for RGB I/F.				
28	DB4	6-bit/pixel: DB[5:0] is used;				
29	DB3	16-bit/pixel: DB[17:13]=R[4:0], DB[11:6]=G[5:0] and DB[5:1]=B[4:0]; 18-bit/pixel: DB[17:12]=R[5:0], DB[11:6]=G[5:0] and DB[5:0]=B[5:0];				
30	DB3 DB2	Connect unused pins to GND.				
31	DB2 DB1					
-						
32	DB0	Outille to take alice ODLUT				
33	SDO	Serial output signal in SPI I/F.				

34	SDI	Serial input signal in SPI I/F.
35	/RD	Reads strobe signal to write data when /RD is "Low" in MPU interface.
36	/WR_RS	MCU: Serves as a write signal and writes data at the rising edge. 4-line SPI: Serves as command or parameter select.
37	RS_SCL	Display data / command selection in 80-series MPU I/F. RS = "0" : Command RS = "1" : Display data. SPI: This pin is used serial interface clock in SPI.
38	/CS	Chip select input pin ("Low" enable) in MPU I/F and SPI I/F.
39	TE	Tearing effect output pin to synchronize MPU to frame writing.
40	IOVCC	I/O power supply.
41	IOVCC	I/O power supply.
42	VCI	System power supply.
43	GND	Power ground
44	CTP_SCL	I2C clock line
45	CTP_SDA	I2C data line
46	CTP_IRQ	Interrupt
47	CTP_RES	CTP reset line
48	GND	Power ground
49	GND	Power ground
50	GND	Power ground

5. Absolute Maximum Ratings

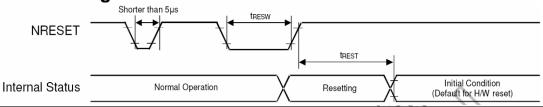
<u> </u>				
Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	4.6	V
Analog Supply Voltage	VCI	-0.3	4.6	V
Input Voltage	Vin	-0.3	IOVCC+0.3	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Тѕт	-30	80	°C
Storage Humidity	HD	20	90	%RH

6. DC Characteristics

Item	Symbol	Min.	Тур.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	1.8/2.8	3.3	٧	-
Analog Supply Voltage	VCI	2.5	2.8	3.3	٧	-
Input High Voltage	V _{IH}	0.7IOVCC	-	IOVCC	V	Digital input pins
Input Low Voltage	V _{IL}	GND	1	0.3IOVCC	V	Digital input pins
Output High Voltage	V _{OH}	0.8IOVCC	1	IOVCC	V	Digital output pins
Output Low Voltage	V_{OL}	GND	-	0.2IOVCC	٧	Digital output pins
I/O Leak Current	lu	-0.1	ı	0.1	uA	-

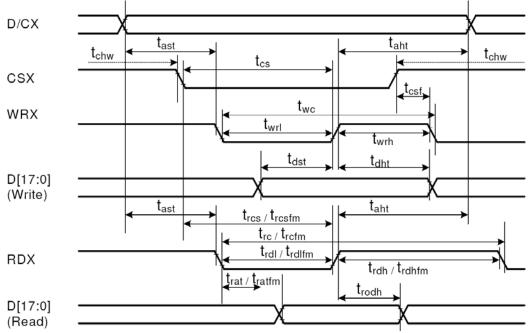
7. Timing Characteristics

7.1 Reset Timing Characteristics



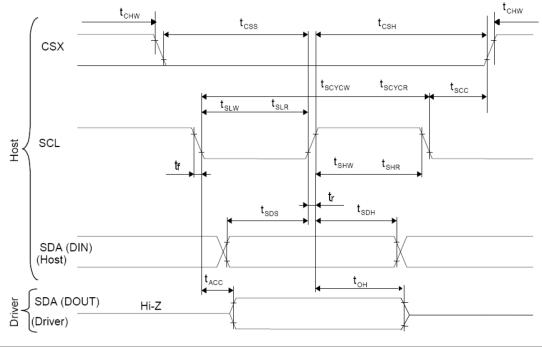
Symbol	Parameter	Related		Spec.		Note	Unit
Syllibol	Faranietei	Pins	Min.	Тур.	Max.	Note	Oilit
tRESW	Reset low pulse width ⁽¹⁾	NRESET	10	-	- (/	<u>-</u>	μs
tREST	Reset complete time ⁽²⁾	-	5	~((A)	When reset applied during SLPIN mode	ms
INEST	neset complete time	-	120	(0))_	When reset applied during SLPOUT mode	ms

7.2 i80-System Interface Timing Characteristics



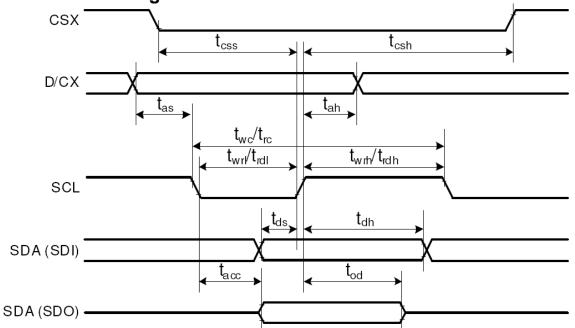
Signal	Symbo I	Parameter	min	max	Unit	Description
DCX	tast	Address setup time	0	-	ns	
DCX	taht	Address hold time (Write/Read)	0	-	ns	
	tchw	CSX "H" pulse width	0	-	ns	
	tcs	Chip Select setup time (Write)	15	-	ns	
CSX	trcs	Chip Select setup time (Read ID)	45	-	ns	
	trcsfm	Chip Select setup time (Read FM)	355	-	ns	
	tcsf	Chip Select Wait time (Write/Read)	10	-	ns	
	twc	Write cycle	66	-	ns	
WRX	twrh	Write Control pulse H duration	15	-	ns	
	twrl	Write Control pulse L duration	15	-	ns	
	trcfm	Read Cycle (FM)	450	-	ns	
RDX (FM)	trdhfm	Read Control H duration (FM)	90	-	ns	
	trdlfm	Read Control L duration (FM)	355	-	ns	
	trc	Read cycle (ID)	160	-	ns	
RDX (ID)	trdh	Read Control pulse H duration	90	-	ns	
	trdl	Read Control pulse L duration	45	-	ns	
D[47.0]	tdst	Write data setup time	10	-	ns	
D[17:0],	tdht	Write data hold time	10	-	ns	For maximum CL=30pF
D[17:10]&D[8:1], D[17:10],	trat	Read access time	-	40	ns	For minimum CL=30pF
D[17:10], D[17:9]	tratfm	Read access time	-	340	ns	1 or minimum oc-opi
J[17.0]	trod	Read output disable time	20	80	ns	

7.3 3-line SPI Timing Characteristics



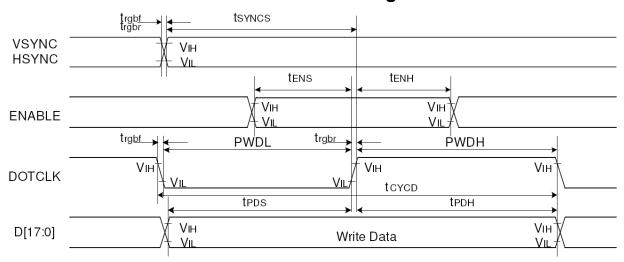
Signal	Symbol	Parameter	min	max	Unit	Description
	tscycw	Serial Clock Cycle (Write)	100	-	ns	
	tshw	SCL "H" Pulse Width (Write)	40	-	ns	
SCL	tslw	SCL "L" Pulse Width (Write)	40	-	ns	
SOL	tscycr	Serial Clock Cycle (Read)	150	-	ns	
	tshr	SCL "H" Pulse Width (Read)	60	-	ns	
	tslr	SCL "L" Pulse Width (Read)	60	-	ns	
SDA / SDI	tsds	Data setup time (Write)	30	-	ns	
(Input)	tsdh	Data hold time (Write)	30	-	ns	
SDA / SDO	tacc	Access time (Read)	10	-	ns	
(Output)	toh	Output disable time (Read)	10	50	ns	
	tscc	SCL-CSX	20	-	ns	
CSX	tchw	CSX "H" Pulse Width	40	-	ns	
USX	tcss	CSX-SCL Time	60	-	ns	
	tcsh	CSX-SOL TITTE	65	-	ns	

7.4 4-line SPI Timing Characteristics



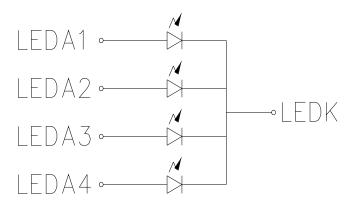
Signal	Symbol	Parameter	min	max	Unit	Description
CSX	tcss	Chip select time (Write)	40	-	ns	
CSX	tcsh	Chip select hold time (Read)	40	-	ns	
	twc	Serial clock cycle (Write)	100	-	ns	
	twrh	SCL "H" pulse width (Write)	40	-	ns	
SCL	twrl	SCL "L" pulse width (Write)	40	-	ns	
SCL	trc	Serial clock cycle (Read)	150	-	ns	
	trdh	SCL "H" pulse width (Read)	60	-	ns	
	trdl	SCL "L" pulse width (Read)	60	-	ns	
D/OV	tas	D/CX setup time	10	-		
D/CX	tah	D/CX hold time (Write / Read)	10	-		
SDA / SDI	tds	Data setup time (Write)	30	-	ns	
(Input)	tdh	Data hold time (Write)	30	-	ns	
SDA / SDO	tacc	Access time (Read)	10	-	ns	For maximum CL=30pF
(Output)	tod	Output disable time (Read)	10	50	ns	For minimum CL=8pF

7.5 Parallel 18/16/6-bit RGB Interface Timing Characteristics



Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC /	tsyncs	VSYNC/HSYNC setup time	15	-	ns	
HSYNC	t _{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t _{ENS}	DE setup time	15	-	ns	
DE	t _{ENH}	DE hold time	15	-	ns	
D[17:0]	t _{POS}	Data setup time	15	-	ns	18/16-bit bus RGB
ال ال ال	t _{PDH}	Data hold time	15	-	ns	interface mode
	PWDH	DOTCLK high-level period	15	-	ns	
DOTCLK	PWDL	DOTCLK low-level period	15	-	ns	
DOTOLK	tcycD	DOTCLK cycle time	100	-	ns	
t_{rgbr} , t_{rgbf}		DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC /	tsyncs	VSYNC/HSYNC setup time	15	-	ns	
HSYNC	t _{SYNCH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t _{ENS}	DE setup time	15	-	ns	
DE	t _{ENH}	DE hold time	15	-	ns	
D[17:0]	t _{POS}	Data setup time	15	-	ns	6-bit bus RGB
D[17:0]	t _{PDH}	Data hold time	15	-	ns	interface mode
	PWDH	DOTCLK high-level pulse period	15	-	ns	
DOTCLK	PWDL	DOTCLK low-level pulse period	15	1	ns	
DOTCER	tcycd	DOTCLK cycle time	100	-	ns	
	t _{rgbr} , t _{rgbf}	tsynch VSYNC/HSYNC hold time 15 tens DE setup time 15 tenh DE hold time 15 tpos Data setup time 15 tpdh Data hold time 15 PWDH DOTCLK high-level period 15 PWDL DOTCLK low-level period 15 tcycd DOTCLK cycle time 100 trgbr, trgbf DOTCLK cycle time 100 tsyncs VSYNC/HSYNC setup time 15 tsynch VSYNC/HSYNC setup time 15 tens DE setup time 15 tens DE setup time 15 tens De hold time 15 tpos Data setup time 15 tpoh Data hold time 15 tpuh Dotclk high-level pulse period 15 PWDL DOTCLK low-level pulse period 15 tcycd DOTCLK cycle time 100	15	ns		

8. Backlight Charasterics



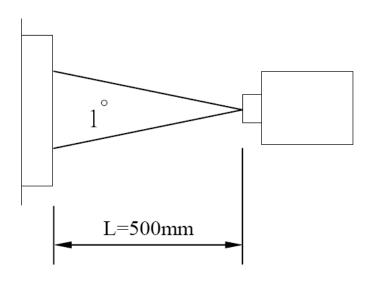
Item	Symbol	MIN	TYP	MAX	UNIT	Test Condition	
Supply Voltage	Vf	2.9	3.2	3.5	V	If=60mA	
Supply Current	If	-	60	80	mA	-	
Luminous Intensity for LCM	-	160	200	-	Cd/m ²	If=60mA	
Uniformity for LCM	-	80	-	-	%	If=60mA	
Life Time	-	20000	-	-	Hr	If=60mA	
Backlight Color	White						

9. Optical Characteristics

(Taransmittance、contrast、RT、viewing angle results are using CPT LC+ CPT EWV Polarizer +Corresponding Backlight, reference only)

ITEM		SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	REMARK	
Transmittance		Т			(5.8)		%		
Contrast Ratio		CR	θ =ψ= 0°		(300)			Note 3	
Response	Response Time		θ =ψ= 0°		(25)		ms	Note 4	
	Upper	Φ			(60)		0		
Viewing	Down		CR≧10		(55)		0	Note 5	
Angle	Right		Un≦ IU		(50)		٥	Note 5	
	Left	Ψ			(50)		٥		
	White	x y Y	θ=φ= 0°	(0.288)	(0.308)	(0.328)			
				(0.319)	(0.339)	(0.359)			
				(27.1)	(30.1)	(33.1)			
	Red	Х	θ=φ= 0°	(0.632)	(0.652)	(0.672)			
		у		(0.311)	(0.331)	(0.351)			
		Ý		(14.8)	(17.8)	(20.8)			
Color Filter		Х		(0.294)	(0.314)	(0.334)		Note 6	
Chromacicity	Green	у	$\theta = \phi = 0^{\circ}$	(0.555)	(0.575)	(0.595)		Note o	
		Ϋ́		(53.7)	(57.7)	(61.7)			
		Х		(0.118)	(0.138)	(0.158)			
	Blue	у	$\theta = \phi = 0^{\circ}$	(0.112)	(0.132)	(0.152)			
		Ý		(11.8)	(14.8)	(17.8)			
	NTSC				(61)		%		

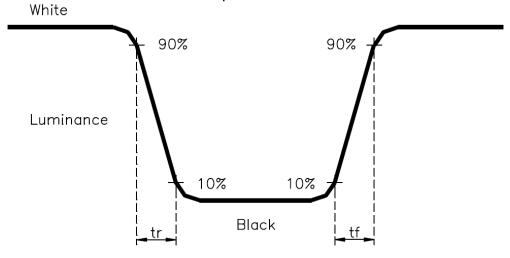
Note 1.Ambient condition: $25^{\circ}C\pm2^{\circ}C$, $60\pm10^{\circ}RH$, under 10 Lunx in the darkroom. Note 2.Measure device: BM-5A (TOPCON), viewing cone= 1 °, IL=20mA.



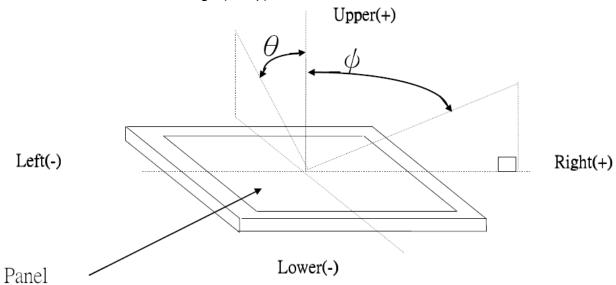
Note 3. Definition of Contrast Ratio:

CR = White Luminance (ON) / Black Luminance (OFF)

Note 4. Definition of response time: The response time is defined as the time interval between the 10% and 90% amplitudes.



Note 5. Definition of view angle(θ , ψ):



Note 6. Light source: C light.

10. Reliability Test Conditions And Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST
1)	High Temperature Storage	80℃±2℃×200Hours	
2	Low Temperature Storage	-30℃±2℃×200Hours	
3	High Temperature Operating	70°C±2°C×120Hours	Inspection after 2~4hours
4	Low Temperature Operating	-20℃±2℃×120Hours	storage at room temperature,the samples should be free from
5	Temperature Cycle(Storage)	$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	defects: 1,Air bublle in the LCD. 2,Sealleak. 3,Non-display. 4,Missing segments.
6	Damp Proof Test (Storage)	50℃±5℃×90%RH×120Hours	5,Glass crack. 6,Current IDD is twice higher than initial value.
7	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5M X,Y,Z direction for total 3hours (Packing Condition)	7,The surface shall be free from damage. 8,The electric charateristic requirements shall be
8	Drooping Test	Drop to the ground from 1M height one time every side of carton. (Packing Condition)	satisfied.
9	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times	

REMARK:

- 1,The Test samples should be applied to only one test item.
- 2, Sample side for each test item is 5~10pcs.
- 3,For Damp Proof Test,Pure water(Resistance $> 10M\Omega$)should be used.
- 4,In case of malfunction defect caused by ESD damage,if it would be recovered to normal state after resetting,it would be judge as a good part.
- 5,EL evaluation should be excepted from reliability test with humidity and temperature:Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.
- 6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

11. Inspection Standard

This standard apply to C-STN/TFT module

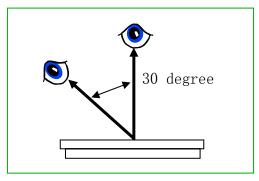
1. Spot check plan:

According to spot check level II,MIL-STD-105D Level II,the rank of accept or reject is below:

3A 级、2A 级:major non-conformance:AQL 0.25 minor non-conformance:AQL 0.4

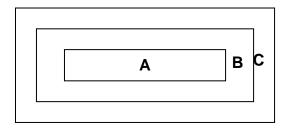
A级: major non-conformance: AQL 0.65 minor non-conformance: AQL 1.

2. Inspection condition:



Under daylight lamp 20 \sim 40W, product distance inspector'eye 30cm,incline degree 30°.

3. LCD area define:



Area A: display area

Area B: VA area

Area C: out of VA area, not in sight after assemby

Remark :non-conformance at area C,but is OK that isn't influence raliability of product & assembly by customer.

4. Inspection standard
4.1 Major non-conformance

NO.	Item	Inspection standard	Rate	
4.1.1	Function non-confor mance	 No display, display abnormaly Miss line, short B/L no function or function abnormaly TP no function 	major	
4.1.2	miss	No matter miss what component	,	
4.1.3	Out of size	Module dimension out of spec		

4.2 Appearance non-conformance

NO.	Item		Inspection standard							
4.2.1		$\Phi = \frac{(x+y)}{2}$								
		A grade								
	Black or white	size (mm	rea	Α	В	С				
	spot	Ф≤0.1	0		ignore			Minor		
	(power on)	0.10<Φ≤	0.15		3					
		0.15<Φ≤	0.20		2	igno	ore			
		0.20<Φ≤	0.25		1					
		0.25<Ф		0						
		Most approv								
		A grade								
		Size(mm)			N	lost approv				
		L(length)	W(w	vidth)	Α	В	С			
	Black or	ignore	W≤	0.03	igı	nore				
4.2.2	white line (power	L≤5.0		3< 0.05	2			Minor		
	on)	L≤3.0		5< 0.07	1		ignore			
			0.07	' <w< td=""><td></td><td>with dot formance</td><td></td><td></td></w<>		with dot formance				
		Most approv	e 3 dar	mages,	line to line	≥10mm		_		

4.2.3	Polarizer position		 polarizer attach meet drawing, disallow out of LCD. polarizer must cover display area (special require unless) 							
		(i) crash at side (remark: S=ITO length) X Y Z								
			≤3.		≪S		gnore			
		(ii) com	Crash di monly sur		extend to ITO	or sea	al.			
4.2.4	LCD non-conf ormance								Minor	
			Х		Υ		Z			
			≤2.0		<frame edge<="" td=""/> <td></td> <th>ignore</th> <th></th> <td></td> <td></td>		ignore			
		(iii) crac Disa	k allow exten	d crac	:k					
				rack		// >//	/			
4.2.5	Contrast voltage warp	VOP/VIc	VOP/VIcd voltage of confirmed sample ± 0.15V						Minor	
4.2.6	color	Color &	Color & luminance of module scope reference spec							
4.2.7	Cross talk	Reference	ce confirm	ed limi	it sample				Minor	

12. Handling Precautions

12.1 Mounting method

The LCD panel of SC LCD module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (CI), Salfur (S)

If goods were sent without being sili8con coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Salfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to Vdd or Vss, do not input any signals before power is turned on, and ground your body, work/assembly areas, assembly equipment to protect against static electricity.

12.4 packing

- Module employ LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the maximum operating temperature, 50%Rh or less is required.

12.6 storage

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it . And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

13. Precaution For Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification
- When a new problem is arisen which is not specified in this specifications
- When an inspection specifications change or operating condition change in customer is reported to GT LCD, and some problem is arisen in this specification due to the change
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method

TBD